N-channel 40 V, 1.4 mΩ standard level MOSFET in LFPAK56E
5 July 2018 Product data sheet

1. General description

Automotive qualified N-channel MOSFET using the latest Trench 9 low ohmic superjunction technology, housed in an enhanced LFPAK56E package. This product has been fully designed and qualified to meet AEC-Q101 requirements delivering high performance and endurance.

2. Features and benefits

- Fully automotive qualified to AEC-Q101:
 - 175 °C rating suitable for thermally demanding environments
- · Trench 9 Superjunction technology:
 - Reduced cell pitch enables enhanced power density and efficiency with lower $R_{\mbox{\scriptsize DSon}}$ in same footprint
 - Improved SOA and avalanche capability compared to standard TrenchMOS
 - Tight V_{GS(th)} limits enable easy paralleling of MOSFETs
- LFPAK Gull Wing leads:
 - High Board Level Reliability absorbing mechanical stress during thermal cycling, unlike traditional QFN packages
 - Visual (AOI) soldering inspection, no need for expensive x-ray equipment
 - · Easy solder wetting for good mechanical solder joint
- LFPAK copper clip technology:
 - Improved reliability, with reduced R_{th} and R_{DSon}
 - · Increases maximum current capability and improved current spreading

3. Applications

- 12 V automotive systems
- · Motors, lamps and solenoid control
- Start-Stop micro-hybrid applications
- · Transmission control
- Ultra high performance power switching

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V_{DS}	drain-source voltage	25 °C ≤ T _j ≤ 175 °C		-	-	40	V
I _D	drain current	V _{GS} = 10 V; T _{mb} = 25 °C; <u>Fig. 2</u>	[1]	-	-	190	Α
P _{tot}	total power dissipation	T _{mb} = 25 °C; <u>Fig. 1</u>		-	-	395	W



Symbol	Parameter	Conditions		Min	Тур	Max	Unit	
Static characte	Static characteristics							
R _{DSon}	drain-source on-state resistance	V_{GS} = 10 V; I_D = 25 A; T_j = 25 °C; Fig. 11		0.74	1.06	1.4	mΩ	
Dynamic chara	Dynamic characteristics							
Q_{GD}	gate-drain charge	I _D = 25 A; V _{DS} = 32 V; V _{GS} = 10 V; Fig. 13; Fig. 14		-	13	27	nC	
Source-drain d	liode							
Q _r	recovered charge	I_S = 25 A; dI_S/dt = -100 A/ μ s; V_{GS} = 0 V; V_{DS} = 20 V		-	39	-	nC	
S	softness factor	I_S = 25 A; dI_S/dt = -100 A/ μ s; V_{GS} = 0 V; V_{DS} = 20 V; T_j = 25 °C		-	0.7	-		

^{[1] 190}A continuous current has been successfully demonstrated during application tests. Practically the current will be limited by PCB, thermal design and operating temperature.

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source		D
2	S	source		
3	S	source		G P A
4	G	gate		mbb076 S
mb	D	mounting base; connected to drain	1 2 3 4 LFPAK56E; Power- SO8 (SOT1023)	

6. Ordering information

Table 3. Ordering information

Type number	Package					
	Name	Description	Version			
BUK7J1R4-40H	LFPAK56E; Power-SO8	plastic, single-ended surface-mounted package (LFPAK56); 4 leads; 1.27 mm pitch	SOT1023			

7. Marking

Table 4. Marking codes

Type number	Marking code
BUK7J1R4-40H	71H440

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V _{DS}	drain-source voltage	25 °C ≤ T _j ≤ 175 °C		-	40	V
V_{GS}	gate-source voltage	DC; T _j ≤ 175 °C		-10	20	V
P _{tot}	total power dissipation	T _{mb} = 25 °C; <u>Fig. 1</u>		-	395	W
I _D	drain current	V _{GS} = 10 V; T _{mb} = 25 °C; <u>Fig. 2</u>	[1]	-	190	Α
		V _{GS} = 10 V; T _{mb} = 100 °C; <u>Fig. 2</u>	[1]	-	190	Α
I _{DM}	peak drain current	pulsed; $t_p \le 10 \mu s$; $T_{mb} = 25 \text{ °C}$; Fig. 3		-	600	А
T _{stg}	storage temperature			-55	175	°C
T _j	junction temperature			-55	175	°C
Source-drain o	liode		•	•	'	
I _S	source current	T _{mb} = 25 °C	[2]	-	145	А
I _{SM}	peak source current	pulsed; $t_p \le 10 \ \mu s$; $T_{mb} = 25 \ ^{\circ}C$		-	600	Α
Avalanche rug	gedness		•		'	'
E _{DS(AL)S}	non-repetitive drain- source avalanche energy	I_D = 190 A; $V_{sup} \le 40$ V; R_{GS} = 50 Ω ; V_{GS} = 10 V; $T_{j(init)}$ = 25 °C; unclamped; Fig. 4	[3] [4]	-	154	mJ

 ¹⁹⁰A continuous current has been successfully demonstrated during application tests. Practically the current will be limited by PCB, thermal design and operating temperature.

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^{[2] 145}A continuous current has been successfully demonstrated during application tests. Practically the current will be limited by PCB, thermal design and operating temperature.

^[3] Single-pulse avalanche rating limited by maximum junction temperature of 175 °C.

^[4] Refer to application note AN10273 for further information.

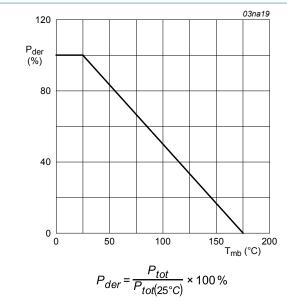
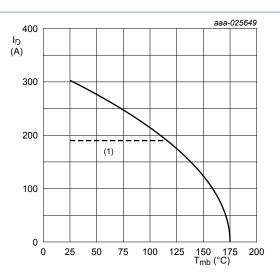


Fig. 1. Normalized total power dissipation as a function of mounting base temperature



 $V_{GS} \ge 10 \text{ V}$ (1) 190A continuous current has been successfully demonstrated during application tests. Practically the current will be limited by PCB, thermal design

Fig. 2. Continuous drain current as a function of mounting base temperature

and operating temperature.

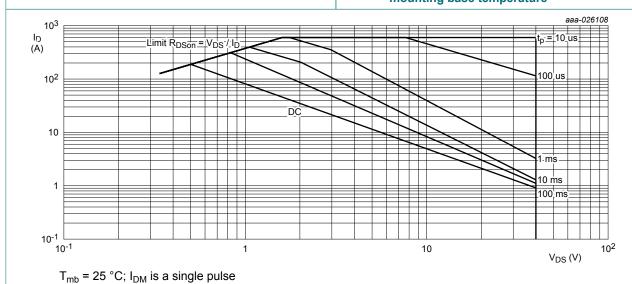
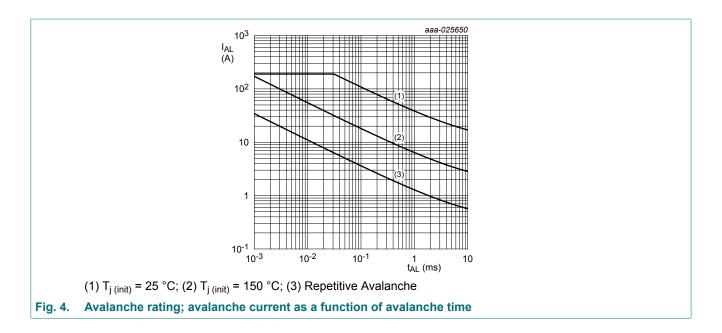


Fig. 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

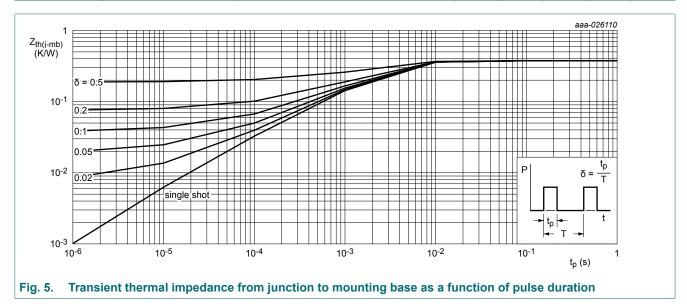
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9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit	
R _{th(j-mb)}	thermal resistance from junction to mounting base	Fig. 5	-	0.29	0.38	K/W	



10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static chara	ncteristics				'	
V _{(BR)DSS}	drain-source	$I_D = 250 \mu A; V_{GS} = 0 V; T_j = 25 °C$	40	42	-	V
	breakdown voltage	I _D = 250 μA; V _{GS} = 0 V; T _j = -40 °C	-	39.6	-	V
		I _D = 250 μA; V _{GS} = 0 V; T _j = -55 °C	36	38.9	-	V
V _{GS(th)}	gate-source threshold voltage	I _D = 1 mA; V _{DS} =V _{GS} ; T _j = 25 °C; <u>Fig. 9</u> ; <u>Fig. 10</u>	2.4	3	3.6	V
		$I_D = 1 \text{ mA; } V_{DS} = V_{GS}; T_j = -55 \text{ °C; } Fig. 9$	-	-	4.3	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 175 \text{ °C}; Fig. 9$	1	-	-	V
I _{DSS}	drain leakage current	V _{DS} = 40 V; V _{GS} = 0 V; T _j = 25 °C	-	0.1	1	μA
		V _{DS} = 16 V; V _{GS} = 0 V; T _j = 125 °C	-	2.4	10	μA
		V _{DS} = 40 V; V _{GS} = 0 V; T _j = 175 °C	-	240	500	μA
I _{GSS}	gate leakage current	V _{GS} = 20 V; V _{DS} = 0 V; T _j = 25 °C	-	2	100	nA
		V _{GS} = -10 V; V _{DS} = 0 V; T _j = 25 °C	-	2	100	nA
R _{DSon}	drain-source on-state resistance	V_{GS} = 10 V; I_{D} = 25 A; T_{j} = 25 °C; Fig. 11	0.74	1.06	1.4	mΩ
		V _{GS} = 10 V; I _D = 25 A; T _j = 105 °C; Fig. 12	1.05	1.57	2.23	mΩ
		V _{GS} = 10 V; I _D = 25 A; T _j = 125 °C; Fig. 12	1.16	1.74	2.45	mΩ
		V _{GS} = 10 V; I _D = 25 A; T _j = 175 °C; Fig. 12	1.46	2.18	3.05	mΩ
R_G	gate resistance	f = 1 MHz; T _j = 25 °C	0.4	1	2.5	Ω
Dynamic ch	aracteristics		·			
Q _{G(tot)}	total gate charge	I _D = 25 A; V _{DS} = 32 V; V _{GS} = 10 V;	-	73	103	nC
Q _{GS}	gate-source charge	Fig. 13; Fig. 14	-	21	32	nC
Q_{GD}	gate-drain charge		-	13	27	nC
C _{iss}	input capacitance	V _{DS} = 25 V; V _{GS} = 0 V; f = 1 MHz;	-	5436	7610	pF
C _{oss}	output capacitance	T _j = 25 °C; <u>Fig. 15</u>	-	1314	1840	pF
C _{rss}	reverse transfer capacitance		-	238	524	pF
t _{d(on)}	turn-on delay time	V_{DS} = 30 V; R_L = 1.2 Ω ; V_{GS} = 10 V;	-	19	-	ns
t _r	rise time	$R_{G(ext)} = 5 \Omega$	-	17	-	ns
t _{d(off)}	turn-off delay time		-	43	-	ns
t _f	fall time		-	21	-	ns
Source-drai	n diode		1		•	
V _{SD}	source-drain voltage	I _S = 25 A; V _{GS} = 0 V; T _j = 25 °C; <u>Fig. 16</u>	-	0.8	1.2	V

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
t _{rr}	reverse recovery time	I_S = 25 A; dI_S/dt = -100 A/ μ s; V_{GS} = 0 V; V_{DS} = 20 V	-	37	-	ns
Q _r	recovered charge		-	39	-	nC
S softi	softness factor	I_S = 25 A; dI_S/dt = -100 A/ μ s; V_{GS} = 0 V; V_{DS} = 20 V; T_j = 25 °C	-	0.7	-	
		I_S = 25 A; dI_S/dt = -500 A/ μ s; V_{GS} = 0 V; V_{DS} = 20 V; T_j = 25 °C	-	0.56	-	

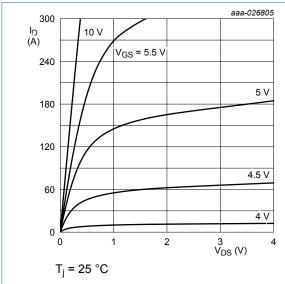


Fig. 6. Output characteristics; drain current as a function of drain-source voltage; typical values

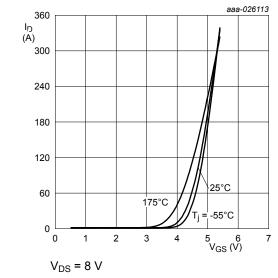


Fig. 8. Transfer characteristics; drain current as a function of gate-source voltage; typical values

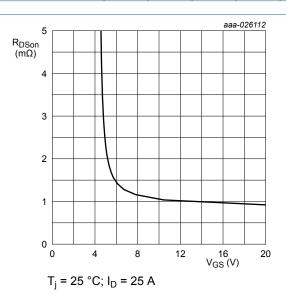


Fig. 7. Drain-source on-state resistance as a function of gate-source voltage; typical values

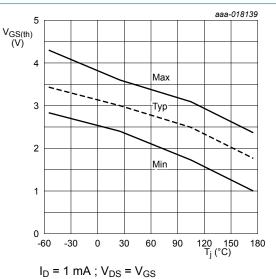


Fig. 9. Gate-source threshold voltage as a function of junction temperature

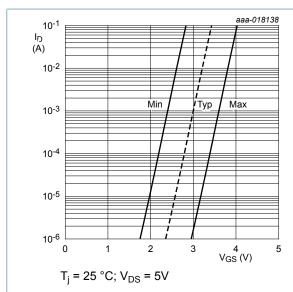


Fig. 10. Sub-threshold drain current as a function of gate-source voltage

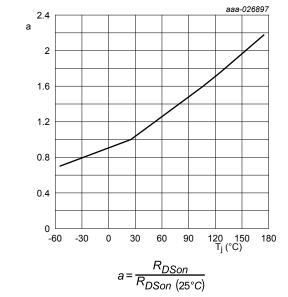


Fig. 12. Normalized drain-source on-state resistance factor as a function of junction temperature

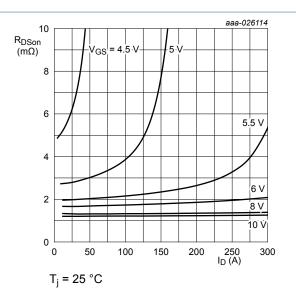


Fig. 11. Drain-source on-state resistance as a function of drain current; typical values

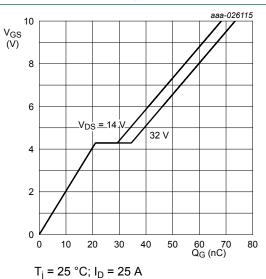


Fig. 13. Gate-source voltage as a function of gate charge; typical values

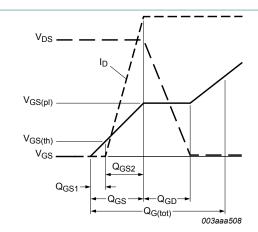
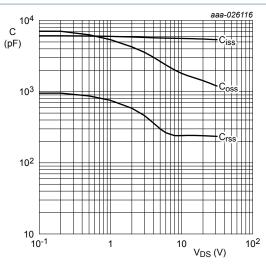


Fig. 14. Gate charge waveform definitions



 $V_{GS} = 0 V; f = 1 MHz$

Fig. 15. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

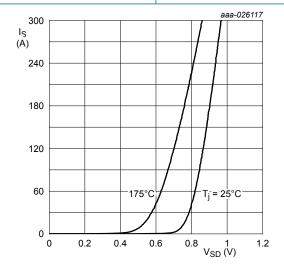
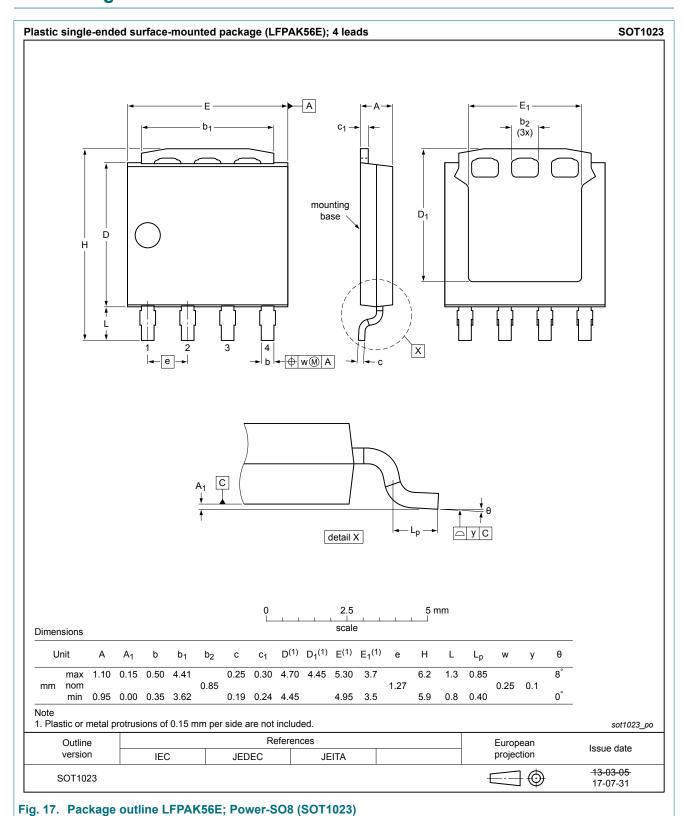


Fig. 16. Source-drain (diode forward) current as a function of source-drain (diode forward) voltage; typical values

 $V_{GS} = 0 V$

11. Package outline



12. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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